

## ABSTRACT OF DISCLOSURE

A process for fabricating a leadless plastic chip carrier includes selectively etching at least a first surface of a leadframe strip to partially define at least a plurality of contact pads and a die attach pad; selectively plating at least one layer of metal on a second surface of the leadframe strip, on an undersurface of at least the plurality of contact pads and the die attach pad; mounting a semiconductor die on the first surface, on the partially defined die attach pad; wire bonding the semiconductor die to ones of the contact pads; encapsulating the wire bonds and the semiconductor die in a molding material such that the molding material covers a first portion of the die attach pad and first portions of the contact pads; selectively etching a second surface of the leadframe strip to define a second portion of the contact pads and a second portion of the die attach pad by etching the second surface with the at least one layer of metal resisting etching; and singulating the leadless plastic chip carrier from the leadframe strip.